### **■ FEATURES**

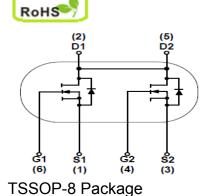
20V/6.5A

RDS(ON)=  $25m\Omega$ @ VGS=4.5V RDS(ON)=  $37m\Omega$ @ VGS=2.5V

- High Cell Desity
- Lead free and Green Device Available
- Application
- Battery pack protection

### **■ PIN DESCRIPTION**





## **Absolute Maximum Ratings** (T<sub>A</sub>=25°C unless otherwise noted)

| Symbol            | Parameter                            | Maximum              | Unit    |    |
|-------------------|--------------------------------------|----------------------|---------|----|
| $V_{DSS}$         | Drain-to-Source Voltage              |                      | 20      | V  |
| $V_{GSS}$         | Gate-to-Source Voltage               | ±10                  | V       |    |
| I <sub>D</sub>    | Continuous Drain Current             | T <sub>C</sub> =25°C | 6       | Α  |
|                   |                                      | T <sub>C</sub> =70°C | 4.8     | Α  |
| I <sub>DP</sub>   | Pulsed Drain Current                 | T <sub>C</sub> =25°C | 20      | Α  |
| PD                | Maximum Power Dissipation            | T <sub>C</sub> =25°C | 1.5     |    |
|                   |                                      | T <sub>C</sub> =70°C | 0.9     |    |
| $T_{J_1} T_{STG}$ | Junction & Storage Temperature Range |                      | -55~150 | °C |

### **Thermal Characteristics**

| Symbol | Parameter                              | Typical | Unit |
|--------|--|---------|------|
| Rθja   | Thermal Resistance-Junction to Ambient | 84      | °C/W |

# SKD8205B 20V N-Channel MOSFET

Electrical Characteristics (TA=25°C unless otherwise noted)

| Symbol                 | Parameter                        | Test Conditions   | Min. | Тур | Max. | Unit |  |  |
|------------------------|----------------------------------|---|------|-----|------|------|--|--|
| Static Characteristics |                                  |   |      |     |      |      |  |  |
| BV <sub>DSS</sub>      | Drain-Source Breakdown Voltage   | $V_{GS}$ =0 $V$ , $I_D$ =250 $u$ A                                      | 20   | _   | _    | V    |  |  |
| 1                      | Zero Gate Voltage Drain Current  | V <sub>DS</sub> =16V,V <sub>GS</sub> =0V                                | _    | _   | 1    | uA   |  |  |
| I <sub>DSS</sub>       |                                  | T <sub>J</sub> =85°C  | _    |     | 10   |      |  |  |
| $V_{GS(th)}$           | Gate Threshold Voltage           | V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250uA                 | 0.5  | 0.7 | 1.2  | V    |  |  |
| I <sub>GSS</sub>       | Gate Leakage Current             | V <sub>GS</sub> =±10V, V <sub>DS</sub> =0V                              |      |     | ±30  | uA   |  |  |
|                        | Drain-Source On-Resistance       | V <sub>GS</sub> =4.5V, I <sub>D</sub> =5A                               |      | 22  | 25   | mΩ   |  |  |
| $R_{DS(on)}^{1}$       |                                  | $V_{GS}$ =2.5V, $I_{D}$ =3A   | _    | 27  | 37   |      |  |  |
| Diode Cha              | racteristics                     |   |      |     |      |      |  |  |
| $V_{SD}^{1}$           | Diode Forward Voltage            | I <sub>SD</sub> =5A,V <sub>GS</sub> =0V                                 | _    | 0.8 | 1.1  | V    |  |  |
| Is                     | Diode Continuous Forward Current |   |      | 5   |      | Α    |  |  |
| Dynamic C              | Characteristics <sup>2</sup>     |   |      |     |      |      |  |  |
| C <sub>iss</sub>       | Input Capacitance                | \/ -0\/ \/ -0\/   | _    | 600 |      | pF   |  |  |
| C <sub>oss</sub>       | Output Capacitance               | -V <sub>GS</sub> =0V, V <sub>DS</sub> =8V<br>-Frequency=1MHz            | _    | 330 |      |      |  |  |
| $C_{rss}$              | Reverse Transfer Capacitance     |   | _    | 140 |      |      |  |  |
| t <sub>d(on)</sub>     | Turn-On Delay Time               |   | _    | 10  |      |      |  |  |
| t <sub>r</sub>         | Turn-On Rise Time                | $V_{DD}$ =10V, $I_{D}$ =1A,<br>$V_{GS}$ =4.5VR <sub>G</sub> =6 $\Omega$ | _    | 11  |      | ns   |  |  |
| t <sub>d(off)</sub>    | Turn-Off Delay Time              |   | _    | 35  |      |      |  |  |
| t <sub>f</sub>         | Turn-Off Fall Time               |   | _    | 30  |      |      |  |  |
| <b>Gate Charg</b>      | e Characteristics <sup>2</sup>   |   |      |     |      |      |  |  |
| $Q_{g}$                | Total Gate Charg                 | -V <sub>DS</sub> =10V,V <sub>GS</sub> =4.5V<br>-I <sub>D</sub> =5A      |      | 10  |      |      |  |  |
| $Q_gs$                 | Gate-to-Source Charge            |   |      | 2.3 |      | nC   |  |  |
| $Q_{gd}$               | Gate-to-Drain Charge             |   |      | 1.5 |      |      |  |  |

Note: 1: Pulse test; pulse width  $\leq$  300ns, duty cycle  $\leq$  2%.

<sup>2:</sup> Guaranteed by design, not subject to production testing.

### **Typical Operating Characteristics**

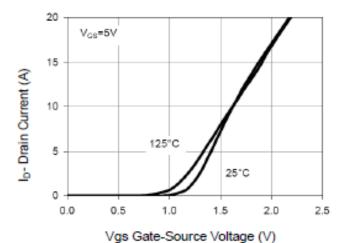
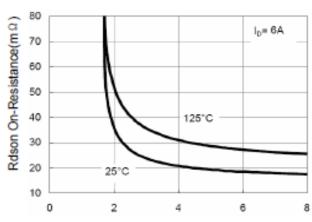
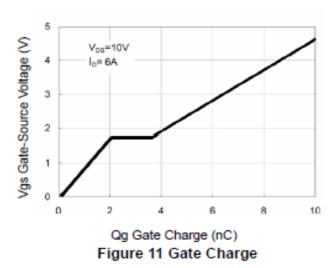


Figure 7 Transfer Characteristics



Vgs Gate-Source Voltage (V) Figure 9 Rdson vs Vgs



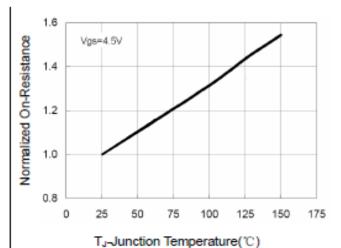
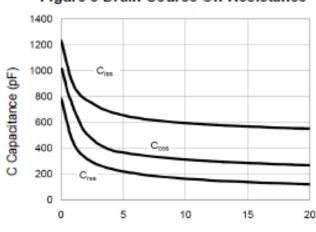


Figure 8 Drain-Source On-Resistance



Vds Drain-Source Voltage (V)
Figure 10 Capacitance vs Vds

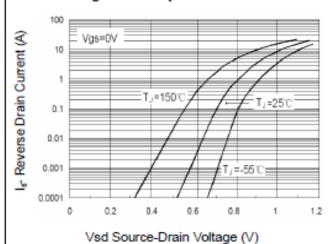


Figure 12 Source- Drain Diode Forward

# **SKD8205B** 20V N-Channel MOSFET

## **Typical Operating Characteristics**

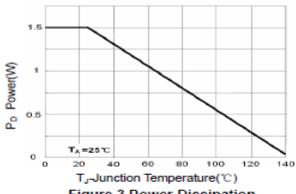


Figure 3 Power Dissipation

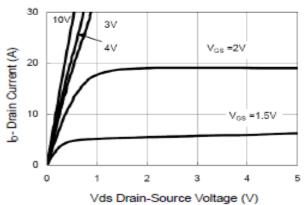


Figure 5 Output CHARACTERISTICS

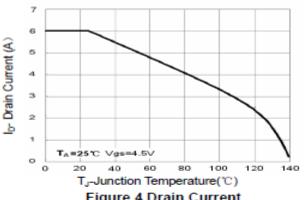


Figure 4 Drain Current

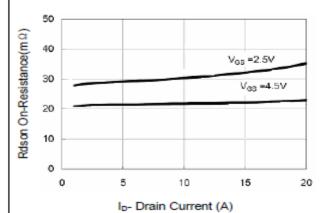


Figure 6 Drain-Source On-Resistance

## **Typical Operating Characteristics**

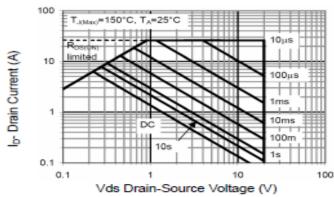


Figure 13 Safe Operation Area

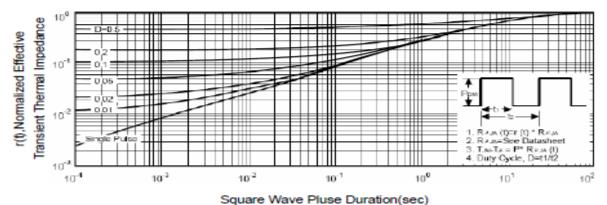


Figure 14 Normalized Maximum Transient Thermal Impedance